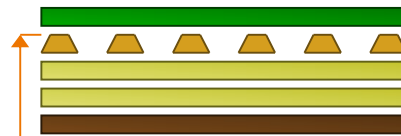
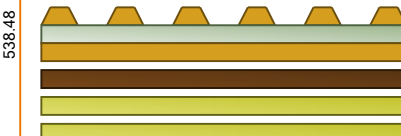
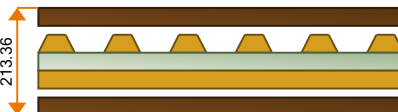


Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID	
1		Photoimageable Solder Mask			17.780		4.000	0.0000		
		Copper Foil	Signal	17.780	35.560					
		FR4 1080 No Flow		63.500	63.500	62.000	4.200	0.0000		
		FR4 1080 No Flow		63.500	63.500	62.000	4.200	0.0000		
2		Coverlay		50.000	50.800		3.500	0.0195		
		Copper Foil	Signal	17.780	17.780					
		Flex Core		75.000	76.200	0.000	4.200	0.0195		
		Copper Foil	Plane	17.780	17.780					
3		Coverlay		50.000	50.800		3.500	0.0195		
		FR4 1080 No Flow		63.500	63.500	62.000	4.200	0.0000		
		FR4 1080 No Flow		63.500	63.500	62.000	4.200	0.0000		
		Copper Foil	Signal	17.780	35.560					
4		Photoimageable Solder Mask			17.780		4.000	0.0000		
		Copper Thickness = 106.680 Dielectric Thickness = 431.800 Solder Mask Thickness = 35.560 Stack Up Thickness = 538.480 Stack Up Thickness with Soldermask = 574.040 Stack Up Cost = 8.50								

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost	
Generic	SM/005	Photoimageable Solder Mask	SolderMask	500-004	2	0.50	1.00	2	1.00	
Generic		Copper Foil	Copper		2	1.00	2.00	2	2.00	
Generic	FR4 1080 NF	FR4 1080 No Flow	PREPREG		4	1.00	4.00	4	4.00	
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00	
Polar Samples	FC/001	Flex Core	Poly	600-001	1	2.00	2.00	1	2.00	
							11.00		11.00	

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 11.00 |
Notes

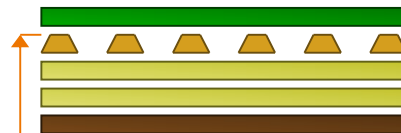
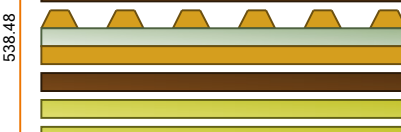
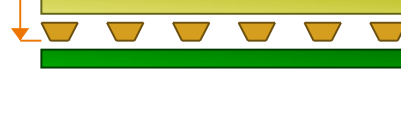
StackName: Rigid 1	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/4	
Date: 27/05/2011	Associated Documents:						
Author: Richard Attrill							
Department: Engineering							
Site:							

Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID	
2		Coverlay		50.000	50.800		3.500	0.0195		
			Signal	17.780	17.780					
3		Flex Core		75.000	76.200	0.000	4.200	0.0195		
			Plane	17.780	17.780					
		Coverlay		50.000	50.800		3.500	0.0195		
Copper Thickness = 35.560 Dielectric Thickness = 177.800 Solder Mask Thickness = 0.000 Stack Up Thickness = 213.360 Stack Up Thickness with Soldermask = 213.360 Stack Up Cost = 4.00										

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost	
Generic	SM/005	Photoimageable Solder Mask	SolderMask	500-004	2	0.50	1.00	2	1.00	
Generic		Copper Foil	Copper		2	1.00	2.00	2	2.00	
Generic	FR4 1080 NF	FR4 1080 No Flow	PREPREG		4	1.00	4.00	4	4.00	
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00	
Polar Samples	FC/001	Flex Core	Poly	600-001	1	2.00	2.00	1	2.00	
							11.00		11.00	

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 11.00 |
Notes

StackName: Flex	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 2/4	
Date: 27/05/2011	Associated Documents:						
Author: Richard Attrill							
Department: Engineering							
Site:							

Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID	
1		Photoimageable Solder Mask			17.780		4.000	0.0000		
		Copper Foil	Signal	17.780	35.560					
		FR4 1080 No Flow		63.500	63.500	62.000	4.200	0.0000		
		FR4 1080 No Flow		63.500	63.500	62.000	4.200	0.0000		
		Coverlay		50.000	50.800		3.500	0.0195		
2		Copper Foil	Signal	17.780	17.780					
Flex Core			75.000	76.200	0.000	4.200	0.0195			
Copper Foil		Plane	17.780	17.780						
Coverlay			50.000	50.800		3.500	0.0195			
FR4 1080 No Flow			63.500	63.500	62.000	4.200	0.0000			
3		FR4 1080 No Flow		63.500	63.500	62.000	4.200	0.0000		
FR4 1080 No Flow			63.500	63.500	62.000	4.200	0.0000			
Copper Foil		Signal	17.780	35.560						
Coverlay			50.000	50.800		3.500	0.0195			
FR4 1080 No Flow			63.500	63.500	62.000	4.200	0.0000			
4		FR4 1080 No Flow		63.500	63.500	62.000	4.200	0.0000		
FR4 1080 No Flow			63.500	63.500	62.000	4.200	0.0000			
Copper Foil		Signal	17.780	35.560						
Coverlay			50.000	50.800		3.500	0.0195			
FR4 1080 No Flow			63.500	63.500	62.000	4.200	0.0000			
		Photoimageable Solder Mask			17.780		4.000	0.0000		
Copper Thickness = 106.680 Dielectric Thickness = 431.800 Solder Mask Thickness = 35.560 Stack Up Thickness = 538.480 Stack Up Thickness with Soldermask = 574.040 Stack Up Cost = 8.50										

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost	
Generic	SM/005	Photoimageable Solder Mask	SolderMask	500-004	2	0.50	1.00	2	1.00	
Generic		Copper Foil	Copper		2	1.00	2.00	2	2.00	
Generic	FR4 1080 NF	FR4 1080 No Flow	PREPREG		4	1.00	4.00	4	4.00	
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00	
Polar Samples	FC/001	Flex Core	Poly	600-001	1	2.00	2.00	1	2.00	
							11.00		11.00	

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 11.00 |
Notes

StackName: Rigid 2	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 3/4	
Date: 27/05/2011	Associated Documents:						
Author: Richard Attrill							
Department: Engineering							
Site:							